

WHAT IS CLAIMED IS:

1. A component material for an electronic device's casing comprising:

5 any one of wood and woody material that has two surfaces;

one of the surfaces of the any one of the wood and woody material which is carbonization-treated to provide a carbonized layer on one surface of the casing; and

10 the other surface of the any one of the wood and woody material which is not carbonization-treated.

2. A component material according to claim 1, wherein the carbonized layer is formed on substantially the whole of one surface of the casing, to provide
15 an electromagnetic shielding characteristic to the casing.

3. A component material according to claim 2, wherein the carbonized layer is formed on the inner surface of the casing.

20 4. A component material according to claim 1, wherein the carbonization treatment is burning.

5. A component material according to claim 4, wherein the carbonized layer is formed on substantially the whole of one surface of the casing to provide
25 an electromagnetic shielding characteristic to the casing.

6. A component material according to claim 5,

wherein the carbonized layer is formed on the inner surface of the casing.

7. A component material, made of any one of wood and woody material, for an electronic device's casing, comprising:

a carbonized layer created by a carbonization treatment; and

a noncarbonized layer not subjected to a carbonization treatment.

8. A component material according to claim 7, wherein the carbonized layer is used for constituting an inner-side surface of the casing.

9. An electronic device comprising:

a substrate configured to have electronic component parts mounted thereon;

a chassis configured to have the substrate mounted thereon; and

a casing configured to cover the substrate-mounted chassis therewith, wherein the casing is made of any one of wood and woody material that has two surfaces, and one of the surfaces of the any one of wood and woody material is carbonization-treated to provide a carbonized layer on one surface of the casing.

10. A method for manufacturing a component material for constructing a casing of an electronic device, comprising:

choosing one surface of any one of wood and woody

material as a surface to be made to one surface of the casing; and

subjecting the chosen surface of the any one of wood and woody material to a carbonization treatment.

5 11. A method according to claim 10, wherein the carbonization-treatment is made by burning.

12. A method according to claim 10, wherein the carbonization-treated surface constitutes an inner-side surface of the casing.